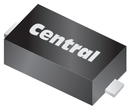
CMDSH2-3F

SURFACE MOUNT SILICON HIGH CURRENT SCHOTTKY DIODE



SOD-323F CASE

www.centralsemi.com

DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMDSH2-3F is a silicon Schottky diode, manufactured in a SOD-323F surface mount package, designed for applications requiring a low forward voltage drop.

MARKING CODE: S2F

MAXIMUM RATINGS: (T_A=25°C)	**SYMBOL**		**UNITS**
Peak Repetitive Reverse Voltage	V_{RRM}	30	V
Continuous Forward Current	I_F	200	mA
Peak Forward Surge Current, tp=10ms	I_{FSM}	1.0	A
Power Dissipation	P_D	225	mW
Operating and Storage Junction Temperature	T_J, T_{stg}	-65 to +150	°C
Thermal Resistance	Θ_{JA}	556	°C/W

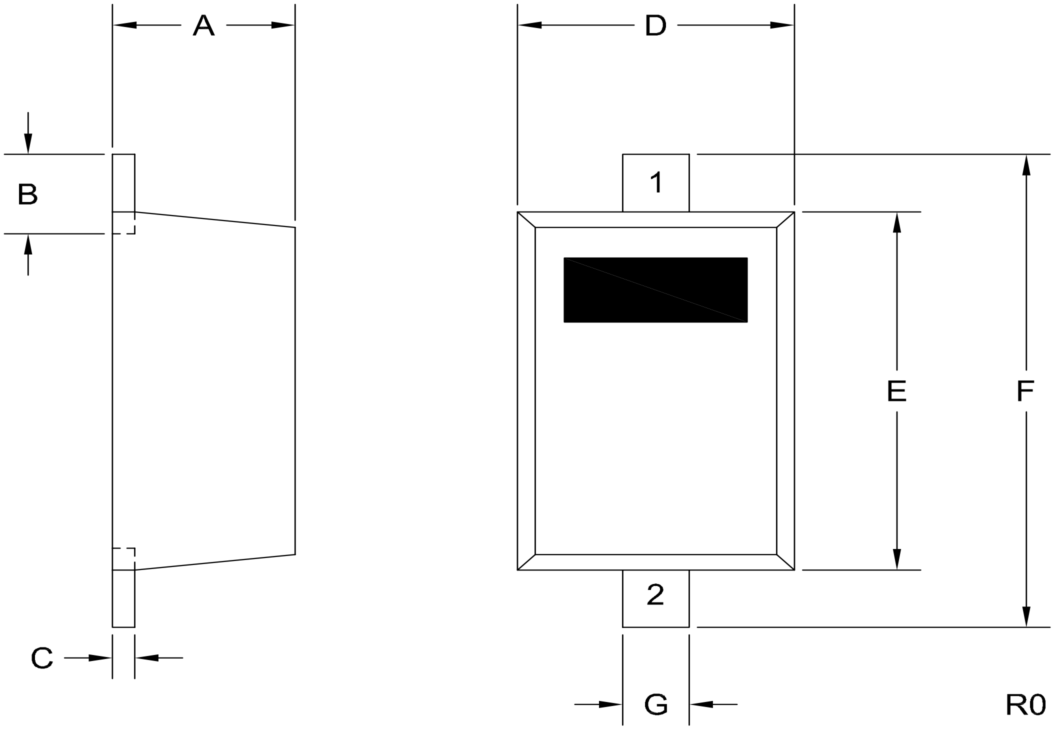
ELECTRICAL CHARACTERISTICS: (T_A=25°C)

SYMBOL	**TEST CONDITIONS**	**MIN**	**TYP**	**MAX**	**UNITS**
I_R	V_R=30V		19	50	μA
BV_R	I_R=100μA	30			V
V_F	I_F=2.0mA		0.186		V
V_F	I_F=15mA		0.245		V
V_F	I_F=100mA		0.35		V
V_F	I_F=200mA		0.42	0.55	V
C_J	V_R=10V, f=1.0MHz		6.0		pF

CMDSH2-3F

**SURFACE MOUNT SILICON
HIGH CURRENT SCHOTTKY DIODE**

SOD-323F CASE - MECHANICAL OUTLINE



LEAD CODE:
1) Cathode
2) Anode

MARKING CODE: S2F

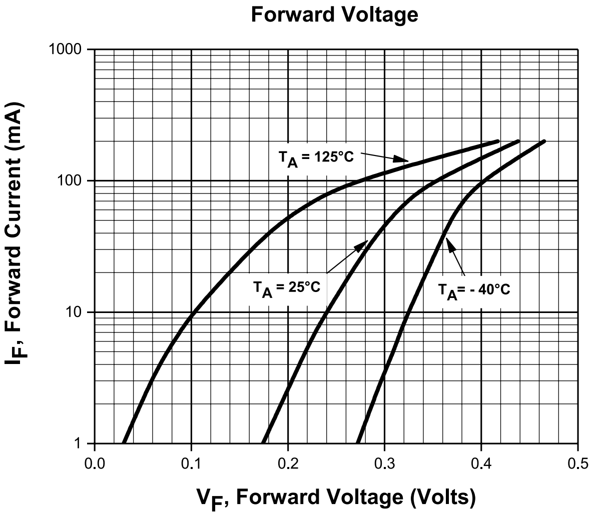
DIMENSIONS				
	INCHES		MILLIMETERS	
SYMBOL	MIN	MAX	MIN	MAX
A	0.028	0.035	0.70	0.90
B	0.012	-	0.30	-
C	0.002	0.006	0.05	0.15
D	0.045	0.053	1.15	1.35
E	0.069	0.077	1.75	1.95
F	0.091	0.106	2.30	2.70
G	0.010	0.014	0.25	0.35
		SOD-323F (REV:R1)		

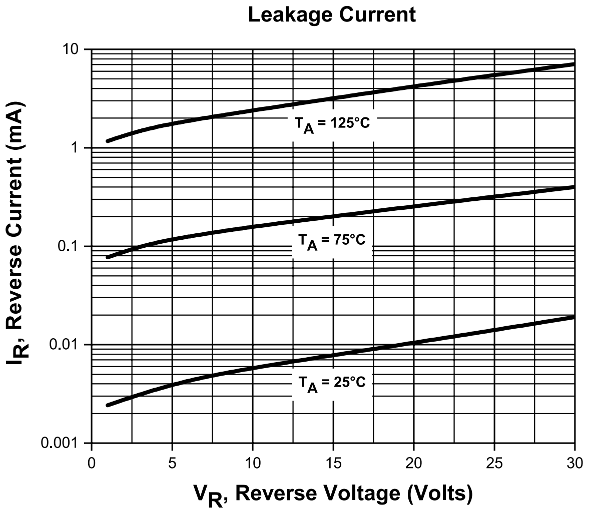
R0 (24-April-2025)

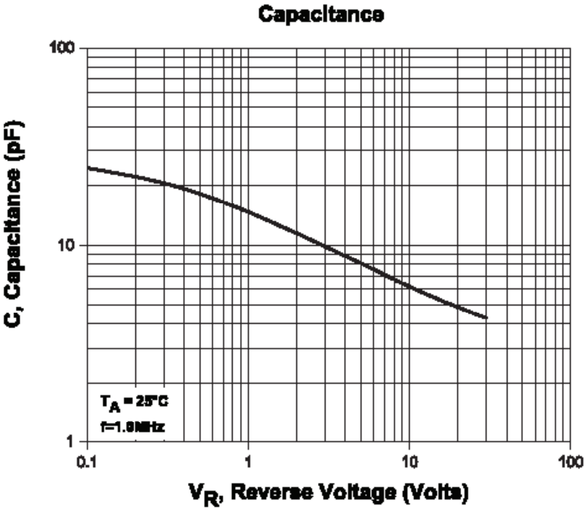
CMDSH2-3F

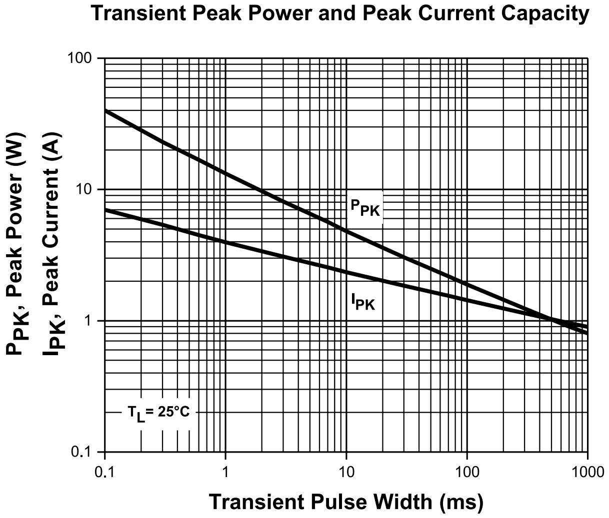
SURFACE MOUNT SILICON HIGH CURRENT SCHOTTKY DIODE

TYPICAL ELECTRICAL CHARACTERISTICS


Forward Voltage


Leakage Current


Capacitance

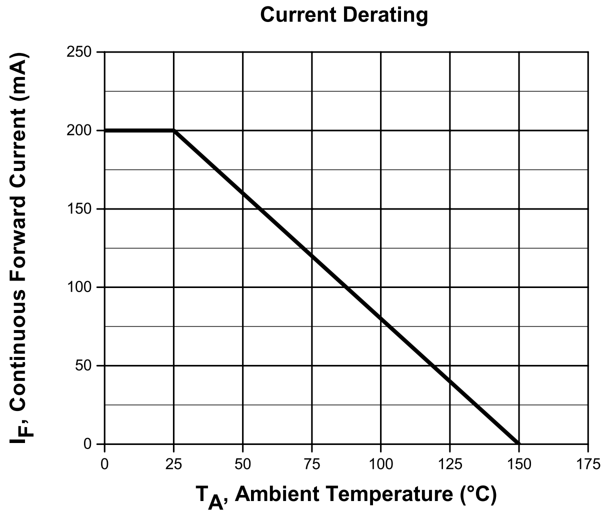

Transient Peak Power and Peak Current Capacity

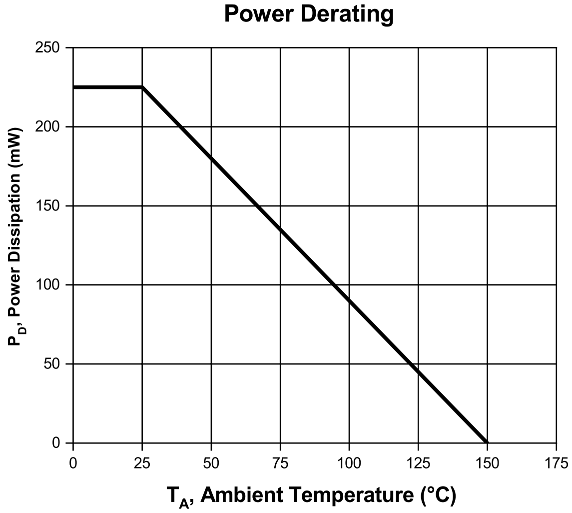
R0 (24-April-2025)

CMDSH2-3F

SURFACE MOUNT SILICON HIGH CURRENT SCHOTTKY DIODE

TYPICAL ELECTRICAL CHARACTERISTICS





R0 (24-April-2025)

OUTSTANDING SUPPORT AND SUPERIOR SERVICES

PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix " TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix " PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

Corporate Headquarters & Customer Support Team

Central Semiconductor Corp.
145 Adams Avenue
Hauppauge, NY 11788 USA
Main Tel: (631) 435-1110
Main Fax: (631) 435-1824
Support Team Fax: (631) 435-3388
www.centralsemi.com

Worldwide Field Representatives:
www.centralsemi.com/wwreps

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